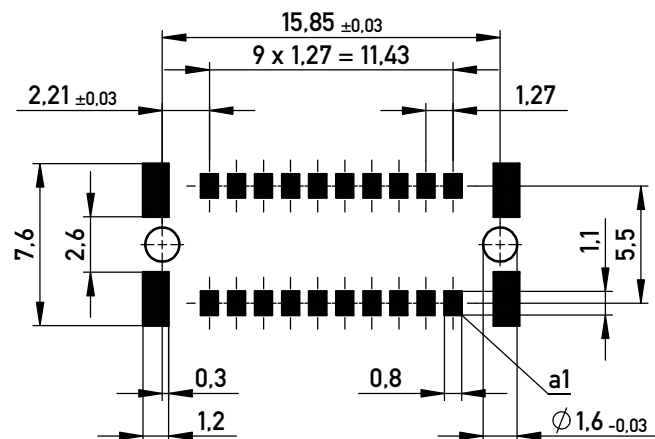


Leiterplatten-Layout Vorschlag für SMT
PCB-Layout Proposal for SMT



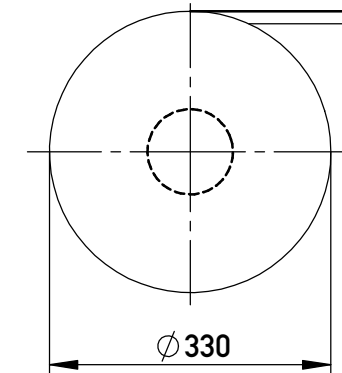
Anforderungsstufe 1
Performance Level 1

Kontaktbereich vergoldet
Mating Area gold plating

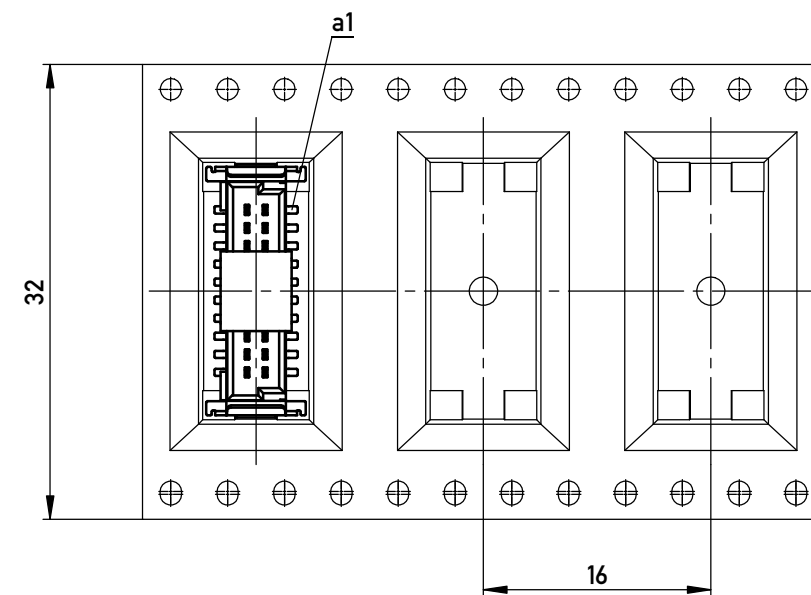
Anschlussbereich verzinkt 4-6 µm
Terminal Area 4-6 µm tin plating

Koplanarität der Anschlüsse ≤ 0.1 mm
Coplanarity Area of Termination ≤ 0.1 mm

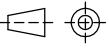

Verpackt im Gurt nach DIN IEC 60286-3
Tape on Reel Packaging according to DIN IEC 60286-3
Verpackungseinheit: 280 Stück
Packaging unit: 280 pcs



Abspulrichtung - Reel off Direction →



BA 8 - 8mm Bauhöhe
type 8-13 - Low Profile

Information: All rights reserved. Only for Information. To ensure that this is the latest version of this drawing, please contact one of the ERNI companies before using.	Tolerances  All Dimensions in mm	Scale 3:1	
	Subject to modification without prior notice. Drawing will not be updated.	Designation Messertl. SMC-Q 20-SMD-BA8-13 Male SMC-Q 20-SMD-type8-13	
 www.ERNI.com	254588		I A3
e Index	14.07.2015 Date	Class SMCQ	

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